Material Declaration Report

PERICOM Semiconductor Corporation
www.pericom.com

Package Type:	**LQFP 64L (10x10mm)**
Pericom Package Code:	**FC64(Pb-free)**
RoHS Compliance:	**Yes**
Applicable Exemption:	**N/A**

Component Weight (mg):	**343.512**
Termination Plating:	**Matte Tin**
JESD 97 Pb-free Category:	**e3**
Plating Thickness (um):	**10~20**
Tin Whisker Mitigation:	**Anneal, 150C/1hr**

MSL Rating:	**3**
Peak Body Temp (C):	**260**
Max Time (sec):	**40**
Reflow Cycles:	**3**
Rev Date:	**7/14/2008**

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	238.400	ASE-Malaysia	Silica Fused	60676-86-0	90.800	216.4672
			Epoxy Resin 1	Proprietary	3.000	7.1520
			Epoxy Resin 2	Proprietary	2.000	4.7680
			Phenolic Resin	Proprietary	3.000	7.1520
			Aromatic Phosphate	Proprietary	1.000	2.3840
			Carbon Black	1333-86-4	0.200	0.4768
LEADFRAME	92.450		Copper (Cu)	7440-50-8	94.900	87.7351
			Nickel (Ni)	7440-02-0	3.200	2.9584
			Silicon (Si)	7440-21-3	0.720	0.6656
			Magnesium (Mg)	7439-95-4	0.180	0.1664
			Silver(Ag)	7440-22-4	1.000	0.9245
SILICON DIE	4.317		Silicon (Si)	7440-21-3	99.192	4.2821
			Non-hazardous Metal	Proprietary	0.808	0.0349
DIE ATTACH EPOXY	0.700		Silver	7440-22-4	76.000	0.5320
			Epoxy Resin	9003-36-5	13.000	0.0910
			t-Butyl pnenyl glycdyl ether	3101-60-8	7.000	0.0490
			Phenolic resin	9003-35-4	3.000	0.0210
			Epoxy silane	2530-83-8	1.000	0.0070
GOLD WIRE	2.330		Gold(Au)	7440-57-5	99.990	2.3298
			Impurities	-	0.010	0.0002
SOLDER PLATING	5.315		Tin (Sn)	7440-31-5	99.990	5.3145
			Impurity	-	0.010	0.0005

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Device	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC

and

China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb	Hg	Cr+6	Cd	PBB	PBDE
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.

X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.